

Issue	Market Index	VIP Interview	Cover Story	IC Market Forces		Components & Modules	Distribution & Supply Chain		Manufacturing & Testing	Capital Market	Purchasing Watch	Expert Opinion	Specials
				IC Observations	IC Short Supply	Components & Modules	Distribution Strategy	Leadtime and Inventory					
January Booking deadline: Nov. 23	•	•	Prospect of semiconductor application trends in 2022	- RF chips	•	MOSFET	Outlook for the distribution market in 2022	•		•	•	•	
February Booking deadline: Dec. 22	•	•	FPGA	- Application Processors	•	CMOS sensor	Distributor survey	•	Wafer manufacturing		•	•	
March Booking deadline: Jan. 22	•	•	Lidar/Millimeter Wave Radar	- Wireless Charging Ics	•	MEMS	Inventory management	•		•	•	•	
April Booking deadline: Feb. 24	•	•	Power management	- Analog IC - DSP	•	- Under-screen fingerprint recognition - Face recognition	Small batch distribution	•	Semiconductor packaging		•	•	
May Booking deadline: Mar. 23	•	•	Charging pile	- GPU	•	- Capacitance - Resistance - Inductance	Digital supply chain	•		•	•	•	
June Booking deadline: Apr. 22	•	•	Machine vision	- RISC V	•	Crystal oscillators	China distributor ranking in 2021	•	IC test		•	•	
July Booking deadline: May 23	•	•	Automobile MCU	- Smart Wear - AR&VR	•	Under-screen camera	Technical distribution	•		•	•	•	
August Booking deadline: June 23	•	•	Big data storage	- Storage controllers	•	Speech recognition	Distribution Capital	•	New manufacturing materials		•	•	
September Booking deadline: July 22	•	•	Smart cockpit	- Display driver ICs	•	- GaN - SiC	Supply Chain Service	•		•	•	•	
October Booking deadline: Aug. 23	•	•	IoT/NB-IoT	- 3D camera	•	- AMOLED display - Flexible display	Domestic substitution	•	PCB manufacturing		•	•	
November Booking deadline: Sept. 19	•	•	5G Mobile Phone	- TWS chipset	•	- Touch Modules - Fingerprint Modules	Supply chain management	•		•	•	•	
December Booking deadline: Oct. 24	•	•	Smart buildings/Smart communities	- 5G base station chips	•	- IGBT - Communication modules	Component e-commerce	•	Automated test		•	•	Distributors and Supply Chain Special Report

Editorial Inquiries

For ESM-China, please contact Clover Lee at email: clover.lee@aspencore.com

Note: The publisher retains the right to reschedule any topic in the calendar.